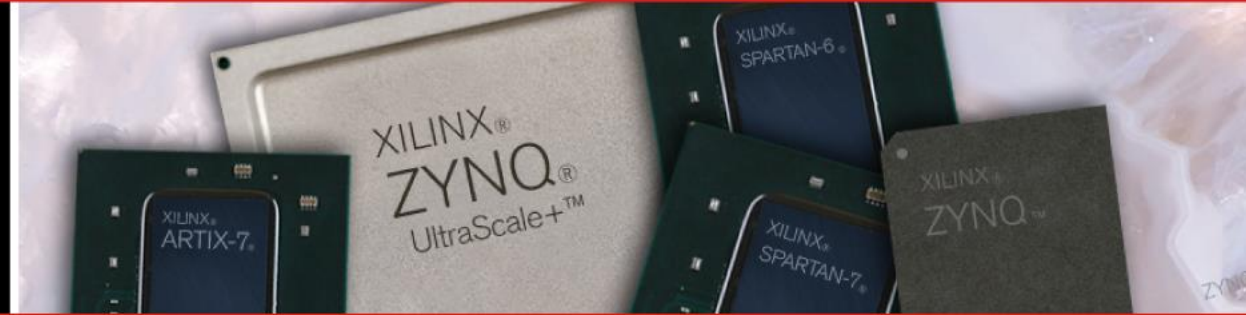
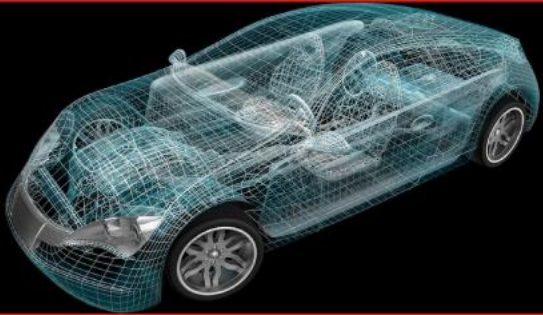


XA Automotive Portfolio Product Selection Guide



SPARTAN.  ARTIX.  KINTEX.  ZYNQ. 

AMD 
XILINX

Automotive SoC Comparison

	XA Zynq UltraScale+™ MPSoC ZU1EG/ZU2EG/ZU3EG/ZU11EG ZU4EV/ZU5EV/ZU7EV Devices	XA Zynq®-7000 SoC Z-7010/7020/7030 Devices
Application Processor	Quad-core Arm® Cortex®-A53 MPCore™ up to 1.2GHz	Dual-core Arm Cortex-A9 MPCore up to 667MHz
Real-Time Processor	Dual-core Arm Cortex-R5 MPCore up to 500MHz	N/A
Graphics Processor	Mali™-400 MP2 up to 600MHz	N/A
External Dynamic Memory Interface	x32/x64: DDR4, LPDDR4, DDR3, DDR3L, LPDDR3 w/ ECC	x16/x32: DDR3L, DDR3, DDR2, LPDDR2 w/ECC (supports 16-bit)
Programmable Logic	103K–653 System Logic Cells	28K–125K Logic Cells
DSP Slices	240–2,928	80–400
Speed Grades	-1, -1L ⁽¹⁾	-1
Automotive Standards	AEC-Q100, Production Part Approval Process	AEC-Q100, Production Part Approval Process
Power Management	Separate Voltage on PS & PL, Full (PL+PS) / Full power domain / Low power domain / Battery Power Domains (PS)	Full (PS +PL), Separate Voltage on PS & PL

Notes: 1. ZU11EG and ZU7EV -1L speed grades are not supported.

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Automotive Device Comparison

	XA Artix [®] -7	XA Kintex [®] -7	XA Spartan [®] -7	XA Spartan-6
Core Voltage	1.0V	1.0V	1.0V	1.2V
Logic Cell	12K–101K	162K	6K–102K	3K–74K
Total Block RAM (K)	720–4,860	2,188	180–4,320	216–3,096
CMTs	3–6	8	2–8	2–6
DSP Slices	40–240	600	10–160	8–132
PCIe [®]	1 @ Gen2 up to x4	1 @ Gen2 up to x 8	0	0–1 @ Gen1 x1
Serial Transceivers	2–4	8	0	0–4
Speed Grades	-1, -2	-1	-1, -2	-2, -3
Automotive Standards	AEC-Q100, Production Part Approval Process	AEC-Q100, Production Part Approval Process	AEC-Q100, Production Part Approval Process	AEC-Q100, Production Part Approval Process

XA Zynq® UltraScale+™ MPSoCs

		Device Name ⁽¹⁾	XAZU1EG	XAZU2EG	XAZU3EG	XAZU11EG	XAZU4EV	XAZU5EV	XAZU7EV
Processing System (PS)	Application	Processor Core	Quad-core Arm® Cortex®-A53 MPCore™ up to 1.2GHz						
	Processor Unit	Memory w/ECC	L1 Cache 32KB I / D per core, L2 Cache 1MB, on-chip Memory 256KB						
	Real-Time	Processor Core	Dual-core Arm Cortex-R5 MPCore up to 500MHz						
	Processor Unit	Memory w/ECC	L1 Cache 32KB I / D per core, Tightly Coupled Memory 128KB per core						
	Graphic & Video	Graphics Processing Unit	Mali™-400 MP2 up to 600MHz						
	Acceleration	Memory	L2 Cache 64KB						
	External Memory	Dynamic Memory Interface	x32/x64: DDR4, LPDDR4, DDR3, DDR3L, LPDDR3 with ECC						
		Static Memory Interfaces	NAND, 2x Quad-SPI						
	Connectivity	High-Speed Connectivity	PCIe® Gen2 x4, 2x USB3.0, SATA 3.1, DisplayPort, 4x Tri-mode Gigabit Ethernet						
		General Connectivity	2xUSB 2.0, 2x SD/SDIO/eMMC, 2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO						
	Integrated Block	Power Management	Full / Low / PL / Battery Power Domains						
		Security	RSA, AES, and SHA						
Functionality	AMS - System Monitor	10-bit, 1MSPS - Temperature, Voltage, and Current Monitor							
PS to PL Interface		12 x 32/64/128b AXI Ports							
Programmable Logic (PL)	Programmable Functionality	System Logic Cells (K)	82	103	154	653	192	256	504
		CLB Flip-Flops (K)	75	94	141	597	176	234	461
		CLB LUTs (K)	37	47	71	299	88	117	230
	Memory	Max. Distributed RAM (Mb)	1.0	1.2	1.8	9.1	2.6	3.5	6.2
		Block RAM Blocks	108	150	216	600	128	144	312
		Total Block RAM (Mb)	3.8	5.3	7.6	21.1	4.5	5.1	11.0
		Ultra RAM Blocks	-	-	-	80	48	64	96
		Ultra RAM (Mb)	-	-	-	22.5	14.0	18.0	27.0
	Clocking	Clock Management Tiles (CMTs)	3	3	3	8	4	4	8
	Integrated IP	DSP Slices	216	240	360	2928	728	1,248	1,728
		VCU	-	-	-	-	1	1	1
		PCI Express Gen 3x16	-	-	-	4	2	2	2
		AMS - System Monitor	1	1	1	1	1	1	1
	Transceivers	GTH 12.5Gb/s Transceivers	-	-	-	32	16	16	16
	Speed Grades	I-Grade ⁽²⁾	-1 (0.85V), -L1 (0.72V)			-1 (0.85V)	-1 (0.85V), -L1 (0.72V)		-1 (0.85V)
Q-Grade		-1 (0.85V)				-1 (0.85V)			

XA Zynq® UltraScale+™ MPSoCs

PS I/Os⁽¹⁾, 3.3V High-Density (HD) I/O, 1.8V High-Performance (HP) I/Os
 PS-GTR 6Gb/s, GTH 12.5Gb/s

Pkg Footprint ⁽²⁾	Dimensions (mm)	XAZU1EG	XAZU2EG	XAZU3EG	XAZU11EG
SBVA484 ⁽³⁾	19x19	170, 24, 58 4, 0	170, 24, 58 4, 0	170, 24, 58 4, 0	
SFVA625 ⁽³⁾	21x21	170, 24, 156 4, 0	170, 24, 156 4, 0	170, 24, 156 4, 0	
SFVC784 ⁽³⁾	23x23	214, 24, 156 4, 0	214, 96, 156 4, 0	214, 96, 156 4, 0	
FFVF1517	40x40				214, 48, 416 4, 32

Pkg Footprint ⁽²⁾	Dimensions (mm)	XAZU4EV	XAZU5EV	XAZU7EV
SBVA484 ⁽³⁾	19x19			
SFVA625 ⁽³⁾	21x21			
SFVC784 ⁽³⁾	23x23	214, 96, 156 4, 4	214, 96, 156 4, 4	
FBVB900	31x31			214, 48, 156 4, 16

Notes:

1. PS I/O is a combination of PS MIO and PS DDRIO.
2. For full part number details, see the Ordering Information section in DS891, *Zynq UltraScale+ MPSoC Overview*.
3. These packages are only offered in 0.8mm ballpitch.

XA Zynq®-7000 SoCs

		Device Name ⁽¹⁾		XA7Z010	XA7Z020	XA7Z030	
Processing System (PS)	Application	Processor Core					Dual Arm® Cortex®-A9 MPCore™ up to 667MHz
	Processor Unit	Processor Extension					NEON™ SIMD Engine and Single/Double Precision Floating Point Unit per Processor
	Memory	L1 Cache		32KB I / D per Core			
		L2 Cache		512KB			
		On-Chip Memory		256KB			
	External Memory	Dynamic Memory Interface		x32/x64: DDR3, DDR3L, DDR2, LPDDR2			
		Static Memory Interfaces		NAND, NOR, 2x Quad-SPI			
	Connectivity	High-Speed Connectivity		2x Tri-mode Gigabit Ethernet			
		General Connectivity		2xUSB 2.0, 2x SD/SDIO/eMMC, 2x UART, 2x CAN 2.0B, 2x I2C, 2x SPI, 4x 32b GPIO			
	Integrated Block Functionality	Security		RSA, AES, and SHA			
AMS - System Monitor		2x12-bit, 1MSPS - Temperature, Voltage, and Current Monitor					
PS to PL Interface		9 x 32/64 AXI Ports					
Programmable Logic (PL)	Programmable Functionality	Xilinx 7 Series PL Equivalent		Artix-7	Artix-7	Kintex-7	
		Logic Cells		28,160	85,280	125,760	
		CLB Flip-Flops		35,300	106,400	157,200	
	Memory	CLB LUTs		17,600	53,300	78,600	
		Total Block RAM (KB)		240	560	1,060	
		(# 36 Kb Blocks)		(60)	(140)	(265)	
	Integrated IP	DSP Slices		80	220	400	
		Peak DSP Performance		100 GMACs	276 GMACs	593 GMACs	
		PCI Express		-	-	Gen2 x4	
		AMS / XADC		AES and SHA 256b Decryption and Authentication for Secure Programmable Configuration			
	Speed Grades	I-Grade		-1			
		Q-Grade		-1			
	Package ⁽¹⁾	Size (mm)	Pitch (mm)	HR I/O ⁽²⁾ , HP I/O ⁽³⁾ , PS I/O ⁽⁴⁾ , GTX Transceiver			
Package	CLG225	13x13	0.8	54, 0, 84, 0			
	CLG400	17x17	0.8	100, 0, 128, 0		125, 0, 128, 0	
	CLG484	19x19	0.8	200, 0, 128, 0			
	FBV484	23x23	1.0	100, 63, 128, 4			

Notes:

1. All packages listed are Pb-free.
2. HR = High Range I/O with support for I/O voltage from 1.2V up to 3.3V.
3. HP = High Performance I/O with support for I/O voltage from 1.2V to 1.8V.
4. PS I/O includes user I/O and DDR I/O.

Important: Verify all data in this document with the device data sheets.

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Transceiver Optimization at the Lowest Cost and Highest DSP Bandwidth (1.0V, 0.95V, 0.9V)

	Part Number	XA7A12T	XA7A15T	XA7A25T	XA7A35T	XA7A50T	XA7A75T	XA7A100T
Logic Resources	Logic Cells	12,800	16,640	23,360	33,280	52,160	75,520	101,440
	Slices	2,000	2,600	3,650	5,200	8,150	11,800	15,850
	CLB Flip-Flops	16,000	20,800	29,200	41,600	65,200	94,400	126,800
Memory Resources	Maximum Distributed RAM (Kb)	171	200	313	400	600	892	1,188
	Block RAM/FIFO w/ ECC (36 Kb each)	20	25	45	50	75	105	135
	Total Block RAM (Kb)	720	900	1,620	1,800	2,700	3,780	4,860
Clock Resources	CMTs (1 MMCM + 1 PLL)	3	5	3	5	5	6	6
I/O Resources	Maximum Single-Ended I/O	150	250	150	250	250	285	285
	Maximum Differential I/O Pairs	72	120	72	120	120	137	137
Embedded Hard IP Resources	DSP Slices	40	45	80	90	120	180	240
	PCIe® Gen2 ⁽¹⁾	1	1	1	1	1	1	1
	Analog Mixed Signal (AMS) / XADC	1	1	1	1	1	1	1
	Configuration AES / HMAC Blocks	1	1	1	1	1	1	1
	GTP Transceivers (6.25Gb/s Max Rate) ⁽²⁾	2	4	4	4	4	4	4
Speed Grades	I-Grade	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2	-1, -2
	Q-Grade	-1	-1	-1	-1	-1	-1	-1
	Package ⁽³⁾	Dimensions (mm)	Ball Pitch (mm)	Available User I/O: 3.3V SelectIO™ HR I/O (GTP Transceivers)				
	CPG236	10 x 10	0.5	106 (2)		106 (2)	106 (2)	
	CPG238	10 x 10	0.5	112 (2)	112 (2)			
	CSG324	15 x 15	0.8	210 (0)		210 (0)	210 (0)	210 (0)
	CSG325	15 x 15	0.8	150 (2)	150 (4)	150 (4)	150 (4)	
	FGG484	23 x 23	1.0				285 (4)	285 (4)

Notes:

1. Supports PCI Express Base 2.1 specification at Gen1 and Gen2 data rates.
2. Represents the maximum number of transceivers available. Note that the CSG324 devices are available without transceivers. See the Package section of this table for details.
3. Device migration is available within the Artix-7 family for like packages but is not supported between other 7 series families.

				Optimized for Best Price-Performance (1.0V, 0.95V, 0.9V)
		Part Number	XA7K160T	
Logic Resources	Logic Cells		162,240	
	Slices		25,350	
	CLB Flip-Flops		202,800	
Memory Resources	Maximum Distributed RAM (Kb)		2,188	
	Block RAM/FIFO w/ ECC (36 Kb each)		325	
	Total Block RAM (Kb)		11,700	
Clock Resources	CMTs (1 MMCM + 1 PLL)		8	
I/O Resources	Maximum Single-Ended I/O		400	
	Maximum Differential I/O Pairs		192	
Embedded Hard IP Resources	DSP Slices		600	
	PCIe® Gen2 ⁽¹⁾		1	
	Analog Mixed Signal (AMS) / XADC		1	
	Configuration AES / HMAC Blocks		1	
Speed Grades	GTX Transceivers (8.0Gb/s Max Rate) ⁽²⁾		8	
	I-Grade		-1	
Package ⁽³⁾	Dimensions (mm)	Ball Pitch (mm)	Available User I/O: 3.3V SelectIO™ HR I/O, 1.8V HP I/O (GTX Transceivers)	
FFG676	27 x 27	1.0	250, 150 (8)	

Notes:

1. Supports PCI Express Base 2.1 specification at Gen1 and Gen2 data rates.
2. Represents the maximum number of transceivers available.
3. Device migration is not supported between other 7 series families.

I/O Optimization at the Lowest Cost and Highest Performance-per-Watt (1.0V)

Part Number	XA7S6	XA7S15	XA7S25	XA7S50	XA7S75	XA7S100
Logic Cells	6,000	12,800	23,360	52,160	76,800	102,400
Slices	938	2,000	3,650	8,151	12,000	16,000
CLB Flip-Flops	7,500	16,000	29,200	65,200	96,000	128,000
Max. Distributed RAM (Kb)	70	150	313	600	832	1,100
Block RAM/FIFO w/ ECC (36Kb each)	5	10	45	75	90	120
Total Block RAM (Kb)	180	360	1,620	2,700	3,240	4,320
Clock Mgmt Tiles (1 MMCM + 1 PLL)	2	2	3	5	8	8
Max. Single-Ended I/O Pins	100	100	150	250	400	400
Max. Differential I/O Pairs	48	48	72	120	192	192
DSP Slices	10	20	80	120	140	160
Analog Mixed Signal (AMS) / XADC	0	0	1	1	1	1
Configuration AES / HMAC Blocks	0	0	1	1	1	1
I-Grade	-1,-2	-1,-2	-1,-2	-1,-2	-1,-2	-1,-2
Q-Grade	-1	-1	-1	-1	-1	-1

Package	Dimensions (mm)	Ball Pitch (mm)	Available User I/O: 3.3V SelectIO™ HR I/O			
CPGA196	8x8	0.5	100	100		
CSGA225	13x13	0.8	100	100	150	
CSGA324	15x15	0.8			150	210
FGGA484	23x23	1.0			250	338
FGGA676	27x27	1.0				400

Transceiver Optimization at the Lowest Cost (1.2V)

		Part Number	XA6SLX4	XA6SLX9	XA6SLX16	XA6SLX25	XA6SLX45	XA6SLX75	XA6SLX100	XA6SLX25T	XA6SLX45T	XA6SLX75T
Logic Resources	Logic Cells		3,840	9,152	14,579	24,051	43,661	74,637	101,262	24,051	43,661	74,637
	Slices		600	1,430	2,278	3,758	6,822	11,662	15,822	3,758	6,822	11,662
	CLB Flip-Flops		4,800	11,440	18,224	30,064	54,576	93,296	126,576	30,064	54,576	93,296
Memory Resources	Maximum Distributed RAM (Kb)		75	90	136	229	401	692	976	229	401	692
	Block RAM (18Kb ea.)		12	32	32	52	116	172	268	52	116	172
	Total Block RAM (Kb)		216	576	576	936	2,088	3,096	4,824	936	2,088	3,096
Clock Resources	CMTs (2 DCM + 1 PLL)		2	2	2	2	4	6	6	2	4	6
Embedded Hard IP Resources	Memory Controller Blocks (Max)		0	2	2	2	2	2	2	2	2	2
	Endpoint Blocks PCIe®		0	0	0	0	0	0	0	1	1	1
	GTP Transceivers (3.2Gb/s Max Rate)		0	0	0	0	0	0	0	2	4	4
	Total I/O Banks		4	4	4	4	4	4	4	4	4	4
	Max User I/O		132	200	232	266	320	328	326	250	296	268
Speed Grades	I-Grade							-2, -3				
	Q-Grade							-2, -3				
Package	Dimensions (mm)	Ball Pitch (mm)	Available User I/O: 3.3V SelectIO™ HR I/O (GTP Transceivers)									
CSG225	13 x 13	0.8	132 (0)	160 (0)	160 (0)							
FTG256	17 x 17	1.0		186 (0)	186 (0)	186 (0)						
CSG324	15 x 15	0.8		200 (0)	232 (0)	226 (0)	218 (0)			190 (2)	190 (4)	
CSG484	19 x 19	0.8					320 (0)	328 (0)				
FGG484	23 x 23	1.0				266 (0)	316 (0)	280 (0)	326 (0)	250 (2)	296 (4)	268 (4)

Device Ordering Information

	XA	ZU	#	E	G	-1	S	B	V	A	484	I
Xilinx Automotive	Generation	Value Index	Processor System	Engine Type	Speed Grade	S: Flip-Chip (.8mm)	F: Lidless	V: RoHS 6/6	Package Designator	Package Pin Count	Temperature Grade (I, Q)	
			E: Dual RPU Quad APU Single GPU	RPU Purpose	-1 = Standard -1L = Low Power		B: Lidless					
	XA	7	Z	###	-1	FB	V	484	Q			
Xilinx Automotive	Generation	Family	Value Index	Speed Grade	CL: Wire-bond (.8 mm)	V: RoHS 6/6	Package Pin Count	Temperature Grade (I, Q)				
				-1 = Standard	FB: Flip-Chip (1 mm)	G: RoHS 6/6						
	XA	7	S	###	-1	FG	G	A	484	Q		
Xilinx Automotive	Generation	Family	Logic Cells in 1K Units	Speed Grade	CP: Wire-bond (.5 mm)	G: RoHS 6/6	Package Designator	Package Pin Count	Temperature Grade (I, Q)			
				-1 = Standard -2 = Medium	FT: Wire-bond (1mm) CS: Wire-bond (.8 mm) FG: Wire-bond (1 mm)							
	XA	7	K	160T	-1	FF	G	676	I			
Xilinx Automotive	Generation	Family	Logic Cells In 1K units	Speed Grade	FF: Wire-bond (1mm)	G: RoHS 6/6	Package Pin Count	Temperature Grade (I, Q)				
				-1 = Standard								
	XA	7	A	###	-1	CP	G	236	I			
Xilinx Automotive	Generation	Family	Logic Cells In 1K units	Speed Grade	CP: Wire-bond (.5mm)	G: RoHS 6/6	Package Pin Count	Temperature Grade (I, Q)				
				-1 = Standard -2 = Medium	CS: Wire-bond (.8mm) FG: Wire-bond (1mm)							
	XA	6	S	LX LXT	###	-1	FG	G	484	Q		
Xilinx Automotive	Generation	Family	Logic Cells in 1K Units	Speed Grade	CS: Wire-bond (.8 mm)	G: RoHS 6/6	Package Pin Count	Temperature Grade (I, Q)				
			LX: Logic LXT: Logic + Transceivers	-2 = Mid -3 = Highest	FT: Wire-bond (1mm) FG: Wire-bond (1 mm)							

I = Tj from -40°C to +100°C ; Q = Tj from -40°C to +125°C

Important: Verify all data in this document with the device data sheets.

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External Memory Controller Maximum Bandwidth (Mb/s)

Core Voltage	XA Zynq® UltraScale+™				XA Zynq-7000				XA Spartan®-7			XA Kintex-7	XA Artix®-7			XA Spartan-6
	-1I/Q (0.85V)		-1L1 (0.72V)		-1I (1.0V)		-1Q (1.0V)		-1I (1.0V)	-1Q (1.0V)	-2I (1.0V)	-1Q (1.0V)	-1I (1.0V)	-1Q (1.0V)	-2I (1.0V)	-2, -3 (1.2V)
	PL	PS	PL	PS	PL	PS	PL	PS	–	–	–	–	–	–	–	–
DDR4	2400	2400	2133	2400	–	–	–	–	–	–	–	–	–	–	–	–
DDR3	2133	2133	1866	2133	800	1066	667	1066	667	667	800	800	800	667	800	800
DDR3L	1866	1866	1600	1866	667	1066	–	1066	667	667	800	800	667	N/A	800	–
DDR2	–	–	–	–	667	800	533	800	667	667	800	667	667	533	800	400
DDR	–	–	–	–	–	355	–	355	–	–	–	–	–	–	–	400
LPDDR4	–	2400	–	2400	–	–	–	–	–	–	–	–	–	–	–	–
LPDDR3	1600	1600	1600	1600	–	–	–	–	–	–	–	–	–	–	–	–
LPDDR2	–	–	–	–	533	800	400	800	–	–	–	533	–	–	–	–
LPDDR	–	–	–	–	–	–	–	–	–	–	–	–	–	–	–	400